

07-16-1998

To the Honorable Commissioner

of the attached original documents or copy thereof.

1. Name of conveying party(ies):



100733133

SEONG JIN KIM

MRD 7-9-98

and address of receiving party(ies):

LG ELECTRONICS INC.
20, Yoido-Dong
Youngdungpo-Ku
Seoul, KOREA

10540 U.S. PTO
09/112299
07/09/98

Additional name(s) of conveying party(ies) attached? yes no Additional name(s) & address(es) attached? Yes No

3. Nature of Conveyance:

Assignment Merger Other _____
 Security Agreement Change of Name Execution Date: July 6, 1998

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date(s) of the application is/are: July 6, 1998

A. Patent Application No.(s)

09112299

B. Patent No.(s)

Additional numbers attached Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

GRAHAM & JAMES LLP
Intellectual Property Group
885 Third Avenue
New York, New York 10022

7. Total fee (37CFR 3.41).....\$ 40.00

Enclosed
 Charge our Deposit Account No. 07-1855 for deficiency in the above fee, and credit any overpayment thereto.

6. Total number of applications and patents involved 1

8. Deposit account number: 07-1855

(Attach duplicate copy of this page if paying by deposit account)

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9. Statment and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Philip M. Weiss
Name of Person Signing

Philip M. Weiss
Signature

July 9, 1998
Date

Reg. no. 34,751

Total number of pages comprising cover sheet: 2

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40.00 DP

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Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks
Box Assignments
Washington, DC 20231

ASSIGNMENT (WORLDWIDE)

WHEREAS, I, **Seong Jin KIM** (hereinafter referred to as ASSIGNOR), have invented and own a certain invention entitled **GLASS CONNECTOR AND FABRICATING METHOD THEREOF** for which application for Letters Patent of the United States has been

 x executed on even date herewith;
 — filed on _____ as Serial No. _____.

WHEREAS, **LG ELECTRONICS INC., 20, Yoido-Dong, Youngdungpo-Ku, Seoul, KOREA** (hereinafter referred to as ASSIGNEE), is desirous of acquiring the entire interest in, to and under said invention and the United States Letters Patent to be obtained therefor;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that in consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration, ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the full and exclusive right, title and interest to the said invention and all Letters Patent of the United States to be obtained therefor on said application or any continuation, division, renewal, substitute or reissue thereof for the full term or terms for which the same may be granted; and all Letters Patent and applications therefor through the world, including all the rights accruing by virtue of the International Convention for the Protection of Industrial Property.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain and enforce said application, said invention and said Letters Patent which may be necessary or desirable to carry out the purposes hereof.

Dated: Jul. 6, 1998.

S. J. Kim
Seong Jin KIM